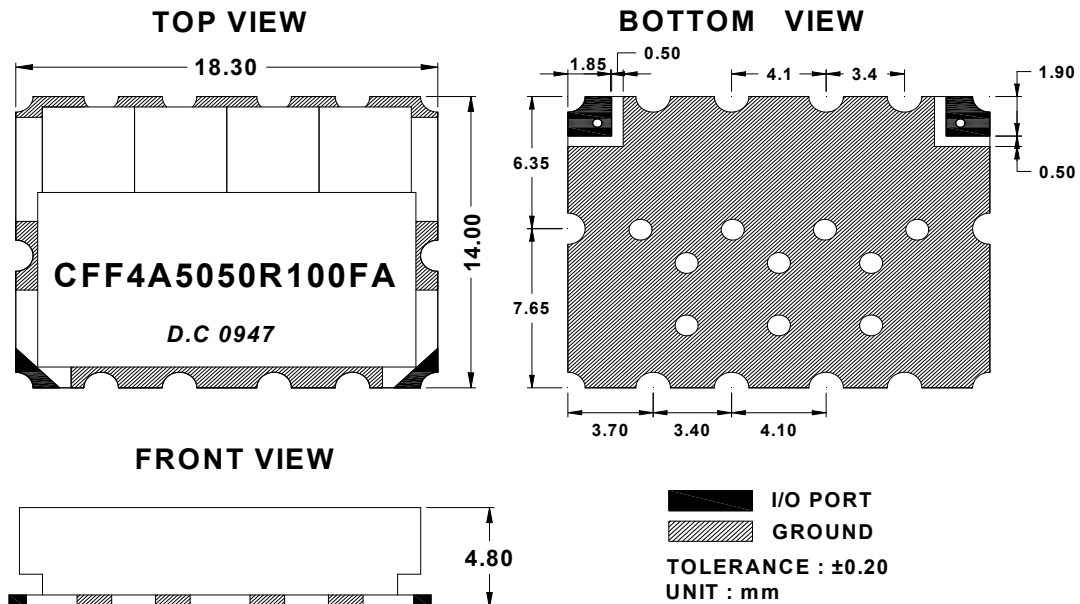


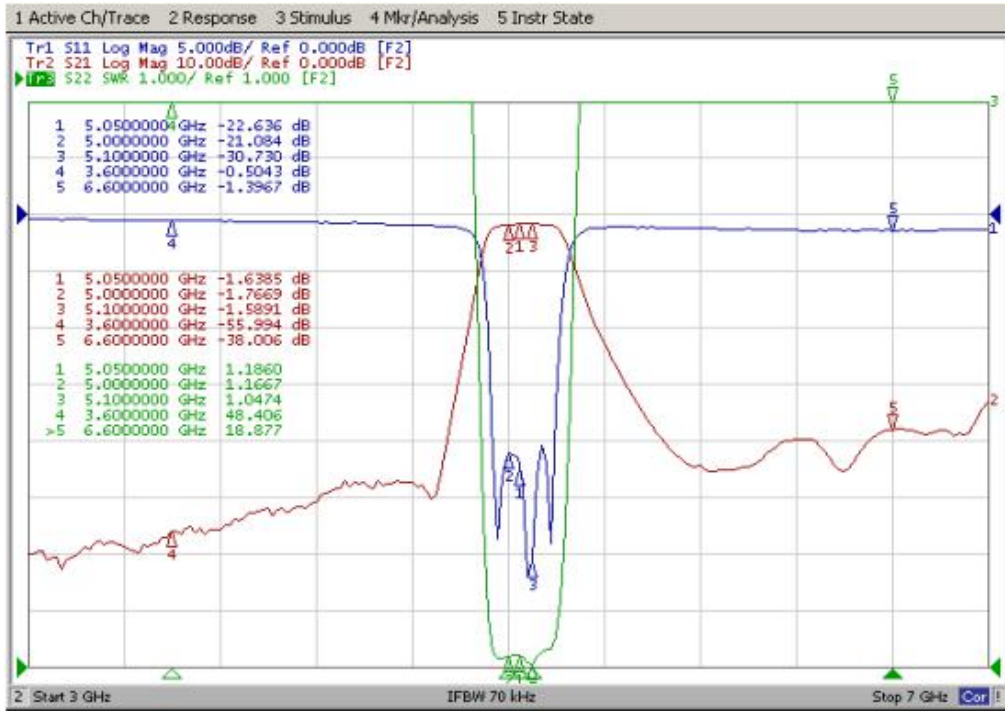
**Electrical Specification**

| ITEMS  | SPEC                               | UNIT   |
|--|------------------------------------|--------|
| Center Frequency [fo]  | 5050.0                             | MHz    |
| Bandwidth [BW]   | fo ±50.0 [5000~5100]               | MHz    |
| Insertion Loss in BW   | 2.5                                | dB max |
| Ripple in BW   | 1.0                                | dB max |
| Return Loss in BW  | 15                                 | dB min |
| Attenuation<br><input checked="" type="checkbox"/> Absolute Value<br><input type="checkbox"/> Relative Value | 30.0 dB min. @ fo ± [6600& 2000.0] | MHz    |
|  | 50.0 dB min. @ fo ± [3600 & ]      | MHz    |
|  | dB min. @ fo ± [4000& 6000]        | MHz    |
|  | dB min. @ fo ± [ & ]               | MHz    |
| Group Delay Variation  |                                    | ns max |
| Input Power  | 3.0                                | W max. |
| In/Out Impedance   | 50 Ω                               |        |
| Operation Temperature Range  | -40°C to +85°C                     |        |

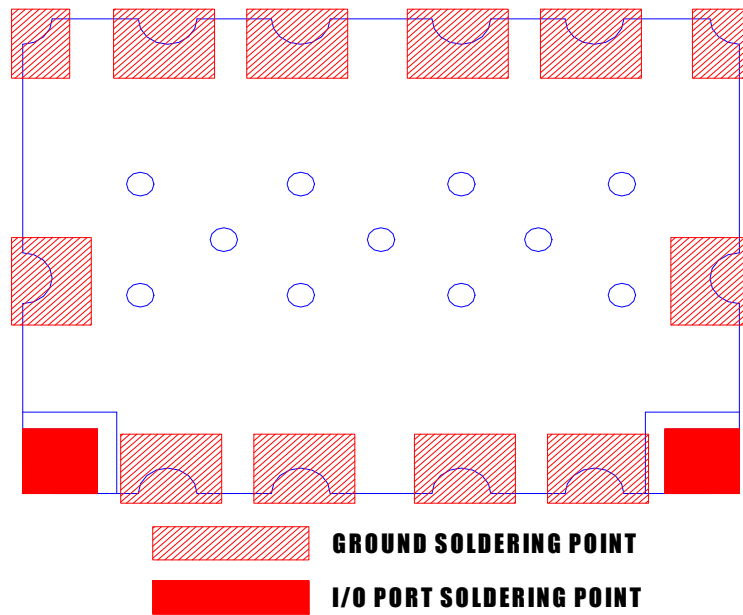
**Mechanical Specification**



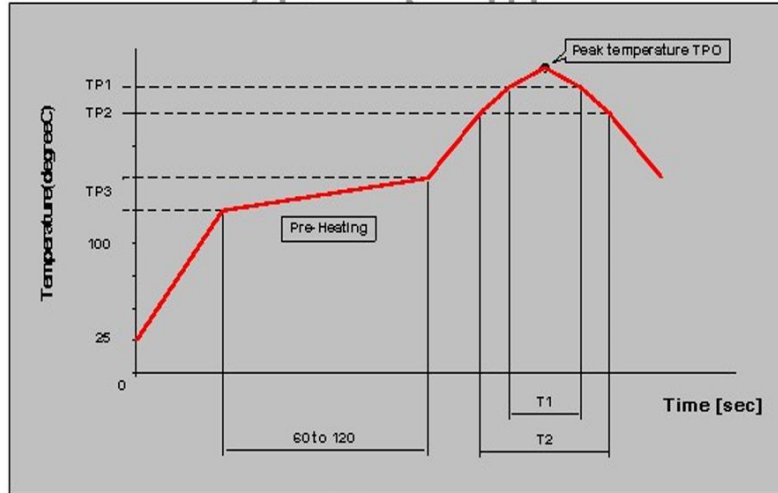
## Plot Data



## Recommended PC Board Pattern



**Soldering Condition**



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

| Reflow standard condition                | TP0 (°C) | TP1 (°C) | T1 (s)   | TP2 (°C) | T2 (s) | TP3 (°C)   |
|--|----------|----------|----------|----------|--------|------------|
| Sn-3Ag-0.5 solder                        | 245±/5   | 220      | 30 to 60 | —        | —      | 150 to 180 |
| Test condition of reflow heat resistance | 260+5/-0 | 240      | 20       | 220      | 70     | 150 to 180 |